FORM PTO-1595 (Modified)



103362229

OVER SHEET

U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

Docket No.: LEE.128

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Tab settings → → ▼	▼
To the Director of the United States Patent and Trac	lemark Office: Please record the attached original documents or copy thereof.
Name of conveying party(ies): Pai-Chou LIU	2. Name and address of receiving party(ies):
Yu-Hsin LEE	Name: Advanced Semiconductor Engineering, Inc. 617
	Address: 26 Chin 3rd Road,
Additional names(s) of conveying party(ies)	₩
3. Nature of conveyance:	
☑ Assignment ☐ Merger	
☐ Security Agreement ☐ Change of	Name City: Kaohsiung State/Prov.:
☐ Other	Country: Taiwan, R.O.C. ZIP:
Execution Date: January 1, 2007	Additional name(s) & address(es) ☐ Yes ☒ No
4. Application number(s) or patent numbers(s):	
If this document is being filed together with a new app	olication, the execution date of the application is: January 1, 2007
Patent Application No. Filing date	B. Patent No.(s)
NEW January 10, 2007	
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Additiona	
Name and address of party to whom corresponder concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Andrew J. Telesz, Jr.	7. Total fee (37 CFR 3.41):\$ 40.00
Registration No. 33,581	☐ Enclosed - Any excess or insufficiency should be
Address: Volentine & Whitt, P.L.L.C.	credited or debited to deposit account
11951 Freedom Drive, Suite 1260	■ ■ Authorized to be charged to deposit account
11/31 Freedom Diffe, Suite 1200	8. Deposit account number:
City: Reston State/Prov.: VA	50-0238
Country: U.S.A. ZIP: 20190	8. Deposit account number:
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9. Statement and signature.	ž.
To the best of my knowledge and belief, the forego of the original document.	ing information is true and correct and any attached copy
Andrew J. Telesz, Jr.	January 19, 2007
Name of Person Signing	Signature \ \ Date 3
Total number of pages in	ocluding cover sheet attachments and document:

ASSIGNMENT

	 In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned 				
Insert Name(s) of	1. Pai-Chou Liu 5.				
Inventor(s)	2. Yu-Hsin Lee 6.				
	3 7				
	4 8				
Insert Name(s) of	the undersigned hereby sell(s) and assign(s) to				
Assignee(s) &	Advanced Semiconductor Engineering, Inc.				
Address(es)	of 26 Chin 3rd Road, Nantze Export Processing Zone Kaohsiung, Taiwan R.O.C.				
Title of	(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as				
Invention	SUBSTRATE STRUCTURE HAVING N-SMD BALL PADS				
Date of Signing of	for which an application for patent in the United States of America has been executed				
Application	the undersigned on 1 January 2007				
	The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.				
•	The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuing. division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.				
	The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.				
	The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.				
	The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.				

VOLENTINE FRANCOS, P.L.L.C. (9/2003)

Page 1 of 2

ASSIGNMENT

	In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned					
Insert Name(s) of	1. Pai-Chou Liu 5.					
Inventor(s)	2. Yu-Hsin Lee 6.					
	3 7					
	48					
Insert Name(s) of	the undersigned hereby sell(s) and assign(s) to					
Assignee(s) &						
Address(es)	of 26 Chin 3 rd Road, Nantze Export Processing Zone Kaohsiung, Taiwan R.O.C.					
(Plate of	(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as					
Title of Invention	SUBSTRATE STRUCTURE HAVING N-SMD BALL PADS					
Date of	for which an application for patent in the United States of America has been executed by					
Signing of Application	the undersigned on 1 January 2007					
	The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.					
	The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuing, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.					
	The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.					
	The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.					
	The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.					

Page I of 2

VOLENTINE	FRANCOS.	P.L.L.C.	. (9/2003)

RECORDED: 01/10/2007

The undersigned hereby grant(s) to Adam C. Volentine, Reg. No. 33,289 and William S. Francos, Reg. No. 38,456, and the firm of VOLENTINE FRANCOS, P.L.L.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

Date	1 January 2007	Signature of Inventor	* pai - chon Lig Pai-Chou Liu
Date	1 January 2007	Signature of Inventor	* Yn Hsin Lee Yu-Hsin Lee
Date		Signature of Inventor	
Date		Signature of Inventor	
Date		_ Signature of Inventor	
Date		Signature of Inventor	
Date		_ Signature of Inventor	
Date		Signature of Inventor	
•	witnessed by at least tw Patent and Trademark (Witness	o witnesses who sign here Office is to record an Assi	that the execution by the Inventor(s) be . However, the current practice of the U.S. gnment even it has not been witnessed.)
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PATENT REEL: 018791 FRAME: 0654